



Thin Wire Wedge-Wedge Bonder 5630i

Bond System

Wire types	Aluminium and gold wire 12,5-75 µm on 2" spool
Bondhead	Wedge-Wedge for thin wire Standard wedges of 1" length, 45° wire feed Motorized wire spool (optional)
Ultrasonic System	F&S Generator 100 kHz (optional 65, 140kHz)

Bonder Base

Axes

- Working area X/Y-axis 100 x 100 mm
- Step resolution 1 µm programmable
- Programmable Z-axis with 60mm stroke

Hardware

- Dual-Core PC with Windows OS Ethernet
- USB 2.0/3.0, LCD Color display 22"
- GigE-CMOS-Color camera
- Network compatible with program archiving

Software

- Single bonds up to complex programs
- Loop shapes can be saved in libraries
- Optional pattern recognition

Placement accuracy: +/- 5 µm @ 3 sigma, incl. Tool / no wire on F&S BONDTEC standard substrate

Repeatability: +/- 3 µm @ 3 sigma, incl. Tool / without wire on F&S BONDTEC standard substrate

Loop height accuracy: +/- 5 µm @ 3 sigma, for thin wire 5630 with 25 µm aluminum wire on F&S BONDTEC standard substrate

Die 56xxi Series:

The semi-automatic Wedge-Wedge Bonder 5630i fills the gap between the manual Wedge to the automatic-bonder. He is on basis 5600i-series fully PC controlled and allows any number of bonds to be programmed.

Pre-programmed adjust points are targeted through the camera's cross hair targeting system and the programmed bonds are executed automatically.

Two operating modes are available: Single bond for repair of various bond samples and making single bonds (manual/automatic) and multi wire for teaching and bonding chips or various bond samples (semi & fully automatic).

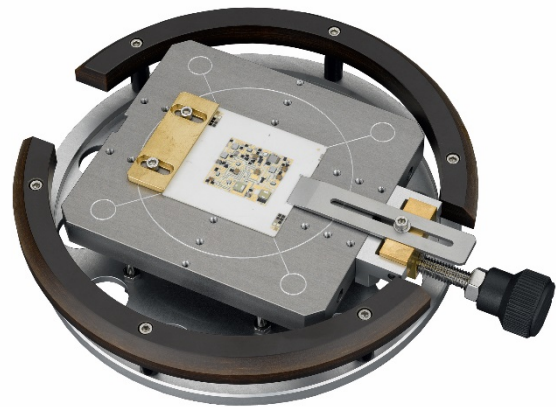
The 5630i can also be used as Gold Wire or Alu Heavy Wire as well as pull-/shear tester by simply replacing the bond head and loading the appropriate software.

Set up time: ~3 minutes.
Ask us for more information!

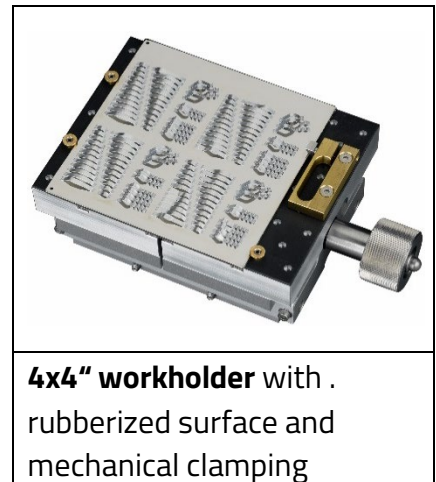
- Speed** 1 wire / 2 - 3 seconds
- Dimensions** W x D x H – 70 x 65x 70 cm, weight approx. 75 kg
- Connections** 100-240 VAC, 1 Phase, 50/60 Hz, max 500 VA
Ø 6mm standard vacuum tubing
- Heater controller** Integrated in the machine 0-250C°

Workholder

Standard-Workholder
for parts up to 4x4"
with Vacuum und mechanical clamping



Optional:



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